

74LVC4245A

Octal dual supply translating transceiver; 3-state

Rev. 10 — 18 December 2012

Product data sheet

1. General description

The 74LVC4245A is an octal dual supply translating transceiver featuring non-inverting 3-state bus compatible outputs in both send and receive directions. It is designed to interface between a 3 V and 5 V bus in a mixed 3 V and 5 V supply environment.

The device features an output enable input (pin $\overline{\text{OE}}$) for easy cascading and a send/receive input (pin DIR) for direction control. Pin $\overline{\text{OE}}$ controls the outputs so that the buses are effectively isolated.

In suspend mode, when $V_{\text{CC(A)}}$ is zero, there will be no current flow from one supply to the other supply. The A-outputs must be set 3-state and the voltage on the A-bus must be smaller than V_{diode} (typical 0.7 V).

$V_{\text{CC(A)}} \geq V_{\text{CC(B)}}$, except in suspend mode.

2. Features and benefits

- 5 V tolerant inputs/outputs, for interfacing with 5 V logic
- Wide supply voltage range:
 - ◆ 3 V bus ($V_{\text{CC(B)}}$): 1.5 V to 3.6 V
 - ◆ 5 V bus ($V_{\text{CC(A)}}$): 1.5 V to 5.5 V
- CMOS low-power consumption
- Direct interface with TTL levels
- Inputs accept voltages up to 5.5 V
- High-impedance when $V_{\text{CC(A)}} = 0$ V
- Complies with JEDEC standard no. JESD8B/JESD36
- ESD protection:
 - ◆ HBM JESD22-A114F exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V
- Multiple package options
- Specified from -40 °C to $+85$ °C and -40 °C to $+125$ °C

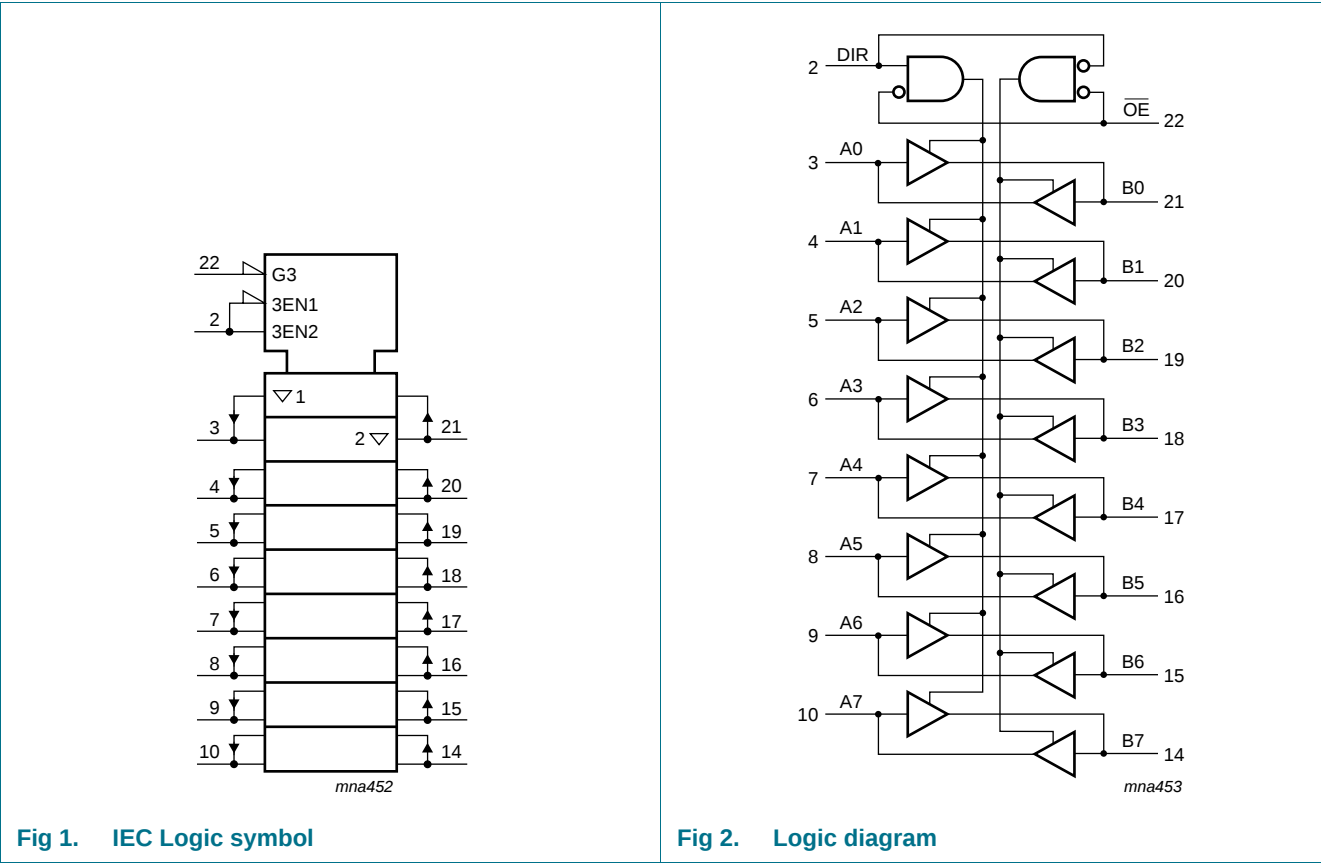


3. Ordering information

Table 1. Ordering information

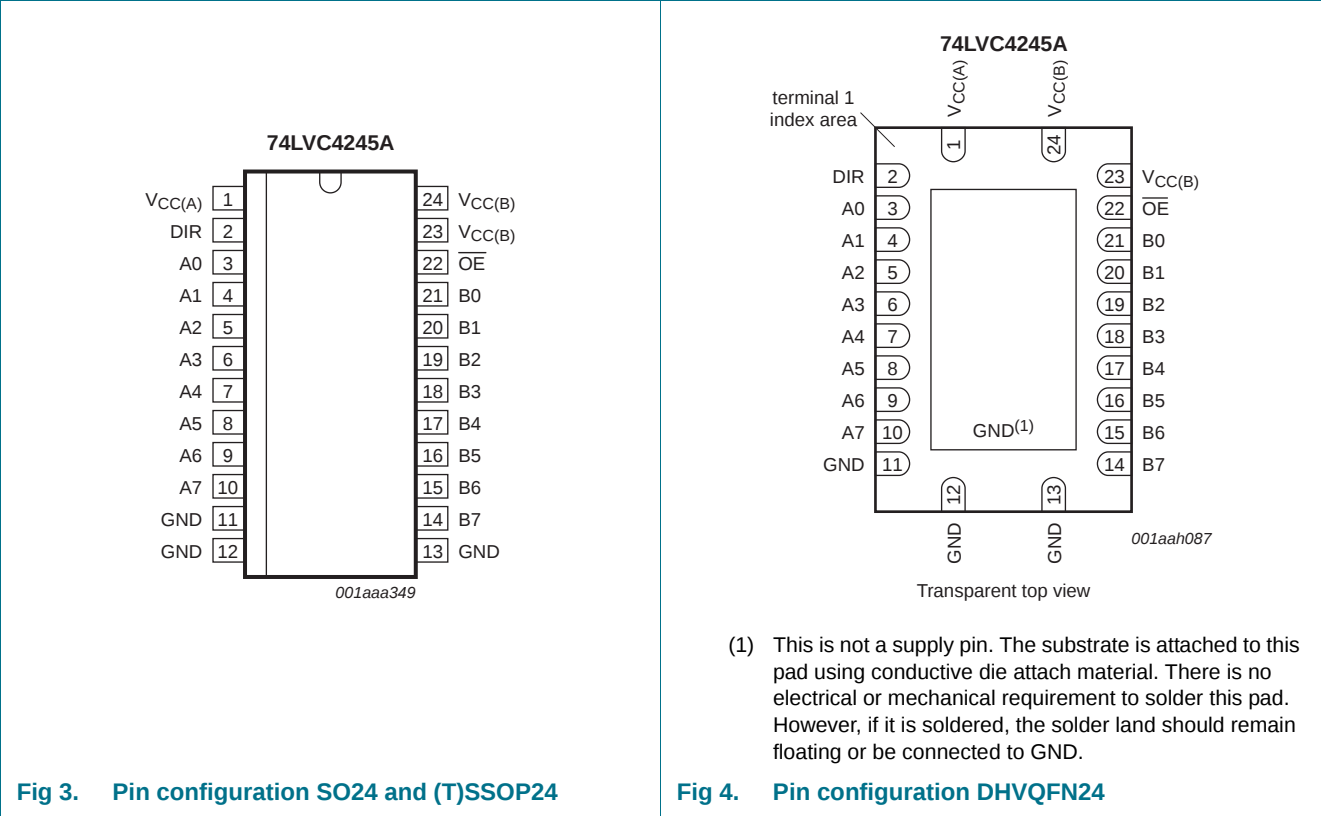
Type number	Package			
	Temperature range	Name	Description	Version
74LVC4245AD	−40 °C to +125 °C	SO24	plastic small outline package; 24 leads; body width 7.5 mm	SOT137-1
74LVC4245ADB	−40 °C to +125 °C	SSOP24	plastic shrink small outline package; 24 leads; body width 5.3 mm	SOT340-1
74LVC4245APW	−40 °C to +125 °C	TSSOP24	plastic thin shrink small outline package; 24 leads; body width 4.4 mm	SOT355-1
74LVC4245ABQ	−40 °C to +125 °C	DHVQFN24	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 24 terminals; body 3.5 × 5.5 × 0.85 mm	SOT815-1

4. Functional diagram



5. Pinning information

5.1 Pinning



5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
V _{CC(A)}	1	supply voltage (5 V bus)
V _{CC(B)}	23, 24	supply voltage (3 V bus)
GND	11, 12, 13	ground (0 V)
DIR	2	direction control
A[0:7]	3, 4, 5, 6, 7, 8, 9, 10	data input or output
B[0:7]	21, 20, 19, 18, 17, 16, 15, 14	data input or output
OE	22	output enable input (active LOW)

6. Functional description

Table 3. Functional table^[1]

Input		Input/output	
OE	DIR	An	Bn
L	L	A = B	input
L	H	input	B = A
H	X	Z	Z

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC(A)}$	supply voltage A		-0.5	+6.5	V
$V_{CC(B)}$	supply voltage B		-0.5	+4.6	V
I_{IK}	input clamping current	$V_I < 0$ V	-50	-	mA
V_I	input voltage		^[1] -0.5	+6.5	V
I_{OK}	output clamping current	$V_O > V_{CCO}$ or $V_O < 0$ V	^[3] -	±50	mA
V_O	output voltage	output HIGH or LOW state	^[1] -0.5	$V_{CC} + 0.5$	V
		output 3-state	^[1] -0.5	+6.5	V
I_O	output current	$V_O = 0$ V to V_{CCO}	^[3] -	±50	mA
I_{CC}	supply current		-	100	mA
I_{GND}	ground current		-100	-	mA
T_{stg}	storage temperature		-65	+150	°C
P_{tot}	total power dissipation	$T_{amb} = -40$ °C to +125 °C	^[2] -	500	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For SO24 packages: above 70 °C the value of P_{tot} derates linearly with 8 mW/K.
 For (T)SSOP24 packages: above 60 °C the value of P_{tot} derates linearly with 5.5 mW/K.
 For DHVQFN24 packages: above 60 °C the value of P_{tot} derates linearly with 4.5 mW/K.

[3] V_{CCO} is the supply voltage associated with the output.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC(A)}$	supply voltage A	$V_{CC(A)} \geq V_{CC(B)}$; see Figure 5 for maximum speed performance	1.5	-	5.5	V
$V_{CC(B)}$	supply voltage B	$V_{CC(A)} \geq V_{CC(B)}$; see Figure 5 for low-voltage applications	1.5	-	3.6	V
V_I	input voltage	for control inputs	0	-	5.5	V

Table 5. Recommended operating conditions ...continued

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _O	output voltage	output HIGH or LOW state	0	-	V _{CC}	V
		output 3-state	0	-	5.5	V
T _{amb}	ambient temperature		-40	-	+125	°C
Δt/ΔV	input transition rise and fall rate	V _{CC(B)} = 2.7 V to 3.0 V	-	-	20	ns/V
		V _{CC(B)} = 3.0 V to 3.6 V	-	-	10	ns/V
		V _{CC(A)} = 3.0 V to 4.5 V	-	-	20	ns/V
		V _{CC(A)} = 4.5 V to 5.5 V	-	-	10	ns/V

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ ^[1]	Max	Unit
T _{amb} = -40 °C to +85 °C						
V _{IH}	HIGH-level input voltage	V _{CC(B)} = 2.7 V to 3.6 V	2.0	-	-	V
		V _{CC(A)} = 4.5 V to 5.5 V	2.0	-	-	V
V _{IL}	LOW-level input voltage	V _{CC(B)} = 2.7 V to 3.6 V	-	-	0.8	V
		V _{CC(A)} = 4.5 V to 5.5 V	-	-	0.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}				
		V _{CC(B)} = 2.7 V to 3.6 V; I _O = -100 μA	V _{CC(B)} - 0.2	V _{CC(B)}	-	V
		V _{CC(B)} = 2.7 V; I _O = -12 mA	V _{CC(B)} - 0.5	-	-	V
		V _{CC(B)} = 3.0 V; I _O = -24 mA	V _{CC(B)} - 0.8	-	-	V
		V _{CC(A)} = 4.5 V to 5.5 V; I _O = -100 μA	V _{CC(A)} - 0.2	V _{CC(A)}	-	V
		V _{CC(A)} = 4.5 V; I _O = -12 mA	V _{CC(A)} - 0.5	-	-	V
		V _{CC(A)} = 4.5 V; I _O = -24 mA	V _{CC(A)} - 0.8	-	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}				
		V _{CC(B)} = 2.7 V to 3.6 V; I _O = 100 μA	-	-	0.20	V
		V _{CC(B)} = 2.7 V; I _O = 12 mA	-	-	0.40	V
		V _{CC(B)} = 3.0 V; I _O = 24 mA	-	-	0.55	V
		V _{CC(A)} = 4.5 V to 5.5 V; I _O = 100 μA	-	-	0.20	V
		V _{CC(A)} = 4.5 V; I _O = 12 mA	-	-	0.40	V
		V _{CC(A)} = 4.5 V; I _O = 24 mA	-	-	0.55	V
I _I	input leakage current	V _I = 5.5 V or GND	-	±0.1	±5	μA
I _{OZ}	OFF-state output current	V _I = V _{IH} or V _{IL} ^[2]				
		V _{CC(B)} = 3.6 V; V _O = V _{CC(B)} or GND	-	±0.1	±5	μA
		V _{CC(A)} = 5.5 V; V _O = V _{CC(A)} or GND	-	±0.1	±5	μA
I _{CC}	supply current	I _O = 0 A				
		V _{CC(B)} = 3.6 V; other inputs at V _{CC(B)} or GND	-	0.1	10	μA
		V _{CC(A)} = 5.5 V; other inputs at V _{CC(A)} or GND	-	0.1	10	μA

Table 6. Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ ^[1]	Max	Unit
ΔI_{CC}	additional supply current	per control pin; $I_O = 0$ A	[3]			
		$V_{CC(B)} = 2.7$ V to 3.6 V; $V_I = V_{CC(B)} - 0.6$ V; other inputs at $V_{CC(B)}$ or GND	-	5	500	μ A
		$V_{CC(A)} = 4.5$ V to 5.5 V; $V_I = V_{CC(A)} - 0.6$ V; other inputs at $V_{CC(A)}$ or GND	-	5	500	μ A
C_I	input capacitance		-	4.0	-	pF
$C_{I/O}$	input/output capacitance	An and Bn	-	5.0	-	pF
$T_{amb} = -40$ °C to $+125$ °C						
V_{IH}	HIGH-level input voltage	$V_{CC(B)} = 2.7$ V to 3.6 V	2.0	-	-	V
		$V_{CC(A)} = 4.5$ V to 5.5 V	2.0	-	-	V
V_{IL}	LOW-level input voltage	$V_{CC(B)} = 2.7$ V to 3.6 V	-	-	0.8	V
		$V_{CC(A)} = 4.5$ V to 5.5 V	-	-	0.8	V
V_{OH}	HIGH-level output voltage	$V_I = V_{IH}$ or V_{IL}				
		$V_{CC(B)} = 2.7$ V to 3.6 V; $I_O = -100$ μ A	$V_{CC(B)} - 0.3$	-	-	V
		$V_{CC(B)} = 2.7$ V; $I_O = -12$ mA	$V_{CC(B)} - 0.65$	-	-	V
		$V_{CC(B)} = 3.0$ V; $I_O = -24$ mA	$V_{CC(B)} - 1.0$	-	-	V
		$V_{CC(A)} = 4.5$ V to 5.5 V; $I_O = -100$ μ A	$V_{CC(A)} - 0.3$	-	-	V
		$V_{CC(A)} = 4.5$ V; $I_O = -12$ mA	$V_{CC(A)} - 0.65$	-	-	V
		$V_{CC(A)} = 4.5$ V; $I_O = -24$ mA	$V_{CC(A)} - 1.0$	-	-	V
V_{OL}	LOW-level output voltage	$V_I = V_{IH}$ or V_{IL}				
		$V_{CC(B)} = 2.7$ V to 3.6 V; $I_O = 100$ μ A	-	-	0.30	V
		$V_{CC(B)} = 2.7$ V; $I_O = 12$ mA	-	-	0.60	V
		$V_{CC(B)} = 3.0$ V; $I_O = 24$ mA	-	-	0.80	V
		$V_{CC(A)} = 4.5$ V to 5.5 V; $I_O = 100$ μ A	-	-	0.30	V
		$V_{CC(A)} = 4.5$ V; $I_O = 12$ mA	-	-	0.60	V
		$V_{CC(A)} = 4.5$ V; $I_O = 24$ mA	-	-	0.80	V
I_I	input leakage current	$V_I = 5.5$ V or GND	-	-	± 20	μ A
I_{OZ}	OFF-state output current	$V_I = V_{IH}$ or V_{IL}	[2]			
		$V_{CC(B)} = 3.6$ V; $V_O = V_{CC(B)}$ or GND	-	-	± 20	μ A
		$V_{CC(A)} = 5.5$ V; $V_O = V_{CC(A)}$ or GND	-	-	± 20	μ A
I_{CC}	supply current	$I_O = 0$ A				
		$V_{CC(B)} = 3.6$ V; other inputs at $V_{CC(B)}$ or GND	-	-	40	μ A
		$V_{CC(A)} = 5.5$ V; other inputs at $V_{CC(A)}$ or GND	-	-	40	μ A

Table 6. Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ ^[1]	Max	Unit
ΔI_{CC}	additional supply current	per control pin; $I_O = 0$ A	[3]			
		$V_{CC(B)} = 2.7$ V to 3.6 V; $V_I = V_{CC(B)} - 0.6$ V; other inputs at $V_{CC(B)}$ or GND	-	-	5000	μ A
		$V_{CC(A)} = 4.5$ V to 5.5 V; $V_I = V_{CC(A)} - 0.6$ V; other inputs at $V_{CC(A)}$ or GND	-	-	5000	μ A

[1] All typical values are measured at $V_{CC(A)} = 5.0$ V, $V_{CC(B)} = 3.3$ V and $T_{amb} = 25$ °C.[2] For transceivers, the parameter I_{OZ} includes the input leakage current.[3] $V_{CC(B)} = 2.7$ V to 3.6 V: other inputs at $V_{CC(B)}$ or GND.
 $V_{CC(A)} = 4.5$ V to 5.5 V: other inputs at $V_{CC(A)}$ or GND.

10. Dynamic characteristics

Table 7. Dynamic characteristicsVoltages are referenced to GND (ground = 0 V). $V_{CC(A)} = 4.5$ V to 5.5 V; $t_r = t_f \leq 2.5$ ns. For test circuit see [Figure 8](#).

Symbol	Parameter	Conditions	$V_{CC(B)}$	-40 °C to +85 °C			-40 °C to +125 °C		Unit
				Min	Typ ^[1]	Max	Min	Max	
t_{PHL}	HIGH to LOW propagation delay	An to Bn; see Figure 6	2.7 V	1.0	3.6	6.3	1.0	8.0	ns
			3.0 V to 3.6 V	1.0	3.3	6.3	1.0	8.0	ns
		Bn to An; see Figure 6	2.7 V	1.0	3.4	6.1	1.0	8.0	ns
			3.0 V to 3.6 V	1.0	3.4	6.1	1.0	8.0	ns
t_{PLH}	LOW to HIGH propagation delay	An to Bn; see Figure 6	2.7 V	1.0	3.3	6.7	1.0	8.5	ns
			3.0 V to 3.6 V	1.0	2.8	6.5	1.0	8.5	ns
		Bn to An; see Figure 6	2.7 V	1.0	3.0	5.0	1.0	6.5	ns
			3.0 V to 3.6 V	1.0	3.0	5.0	1.0	6.5	ns
t_{PZL}	OFF-state to LOW propagation delay	$\overline{OE}$ to An; see Figure 7	2.7 V	1.0	4.5	9.0	1.0	11.5	ns
			3.0 V to 3.6 V	1.0	4.5	9.0	1.0	11.5	ns
		$\overline{OE}$ to Bn; see Figure 7	2.7 V	1.0	4.4	8.7	1.0	11.0	ns
			3.0 V to 3.6 V	1.0	3.8	8.1	1.0	10.5	ns
t_{PZH}	OFF-state to HIGH propagation delay	$\overline{OE}$ to An; see Figure 7	2.7 V	1.0	4.5	8.1	1.0	10.5	ns
			3.0 V to 3.6 V	1.0	4.5	8.1	1.0	10.5	ns
		$\overline{OE}$ to Bn; see Figure 7	2.7 V	1.0	4.3	8.7	1.0	11.0	ns
			3.0 V to 3.6 V	1.0	3.2	8.1	1.0	10.5	ns
t_{PLZ}	LOW to OFF-state propagation delay	$\overline{OE}$ to An; see Figure 7	2.7 V	1.0	2.9	7.0	1.0	9.0	ns
			3.0 V to 3.6 V	1.0	2.9	7.0	1.0	9.0	ns
		$\overline{OE}$ to Bn; see Figure 7	2.7 V	1.0	3.9	7.7	1.0	10.0	ns
			3.0 V to 3.6 V	1.0	3.5	7.7	1.0	10.0	ns
t_{PHZ}	HIGH to OFF-state propagation delay	$\overline{OE}$ to An; see Figure 7	2.7 V	1.0	2.8	5.8	1.0	7.5	ns
			3.0 V to 3.6 V	1.0	2.8	5.8	1.0	7.5	ns
		$\overline{OE}$ to Bn; see Figure 7	2.7 V	1.0	3.3	7.8	1.0	10.0	ns
			3.0 V to 3.6 V	1.0	2.9	7.8	1.0	10.0	ns

Table 7. Dynamic characteristics ...continued

Voltages are referenced to GND (ground = 0 V). $V_{CC(A)} = 4.5\text{ V to }5.5\text{ V}$; $t_r = t_f \leq 2.5\text{ ns}$. For test circuit see [Figure 8](#).

Symbol	Parameter	Conditions	$V_{CC(B)}$	-40 °C to +85 °C			-40 °C to +125 °C		Unit
				Min	Typ ^[1]	Max	Min	Max	
$t_{sk(o)}$	output skew time		^[2]	-	-	1.0	-	1.5	ns
C_{PD}	power dissipation capacitance	5 V bus: Bn to An; $V_I = \text{GND to } V_{CC(A)}$; $V_{CC(A)} = 5.0\text{ V}$	^[3]						
		outputs enabled	-	-	17	-	-	-	pF
		outputs disabled	-	-	5	-	-	-	pF
		3 V bus: An to Bn; $V_I = \text{GND to } V_{CC(B)}$; $V_{CC(B)} = 3.3\text{ V}$	^[3]						
		outputs enabled	-	-	17	-	-	-	pF
		outputs disabled	-	-	5	-	-	-	pF

[1] Typical values are measured at $T_{amb} = 25\text{ °C}$, $V_{CC(A)} = 5.0\text{ V}$, and $V_{CC(B)} = 2.7\text{ V}$ and 3.3 V respectively.

[2] Skew between any two outputs of the same package switching in the same direction. This parameter is guaranteed by design.

[3] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:

f_i = input frequency in MHz; f_o = output frequency in MHz

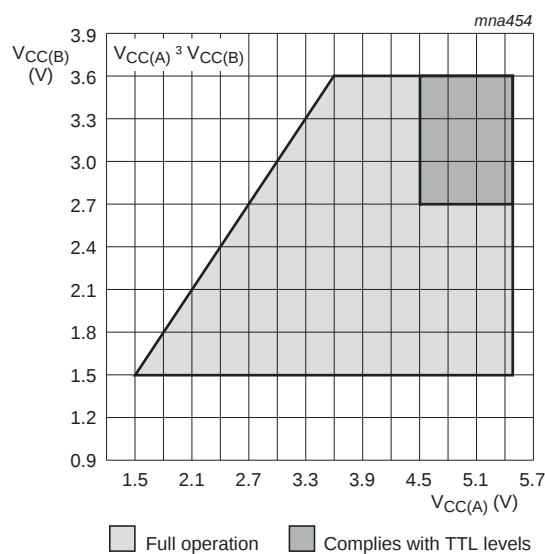
C_L = output load capacitance in pF

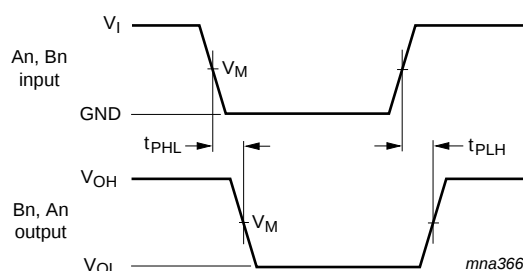
V_{CC} = supply voltage in Volts

N = number of inputs switching

$\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs

11. AC waveforms

**Fig 5. Supply operation area**

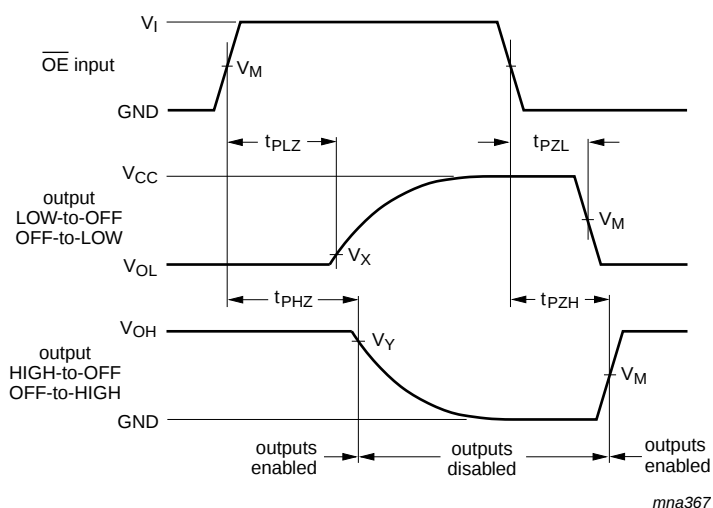


$V_M = 1.5 \text{ V}$ at $2.7 \text{ V} \leq V_{CC(B)} \leq 3.6 \text{ V}$;

$V_M = 0.5 V_{CC(A)}$ at $V_{CC(A)} \geq 4.5 \text{ V}$.

V_{OL} and V_{OH} are typical output voltage drops that occur with the output load.

Fig 6. Input (An, Bn) to output (Bn, An) propagation delays



$V_M = 1.5 \text{ V}$ at $2.7 \text{ V} \leq V_{CC(B)} \leq 3.6 \text{ V}$;

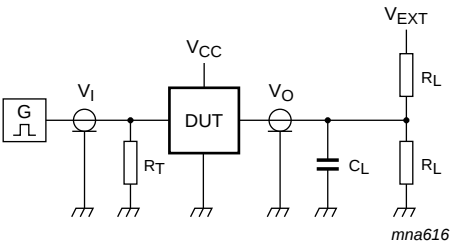
$V_M = 0.5 V_{CC(A)}$ at $V_{CC(A)} \geq 4.5 \text{ V}$.

$V_X = V_{OL} + 0.3 \text{ V}$ at $V_{CC(B)} \geq 2.7 \text{ V}$;

$V_Y = V_{OH} - 0.3 \text{ V}$ at $V_{CC(B)} \geq 2.7 \text{ V}$.

V_{OL} and V_{OH} are typical output voltage drops that occur with the output load.

Fig 7. 3-state enable and disable times



Test data is given in [Table 8](#). Definitions for test circuit:
 R_L = Load resistance.
 C_L = Load capacitance including jig and probe capacitance.
 R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

Fig 8. Load circuitry for switching times

Table 8. Test data

Supply voltage		Input	Load		V_{EXT}		
$V_{CC(A)}$	$V_{CC(B)}$	V_I [1]	C_L	R_L	t_{PLH}, t_{PHL}	t_{PZH}, t_{PHZ}	t_{PZL}, t_{PLZ} [2]
< 2.7 V	< 2.7 V	V_{CCI}	50 pF	500 Ω	open	GND	$2 \times V_{CCO}$
-	2.7 V to 3.6 V	2.7 V	50 pF	500 Ω	open	GND	$2 \times V_{CCO}$
4.5 V to 5.5 V	-	3.0 V	50 pF	500 Ω	open	GND	$2 \times V_{CCO}$

[1] V_{CCI} is the supply voltage associated with the data input port.
[2] V_{CCO} is the supply voltage associated with the output port.

12. Package outline

SO24: plastic small outline package; 24 leads; body width 7.5 mm SOT137-1

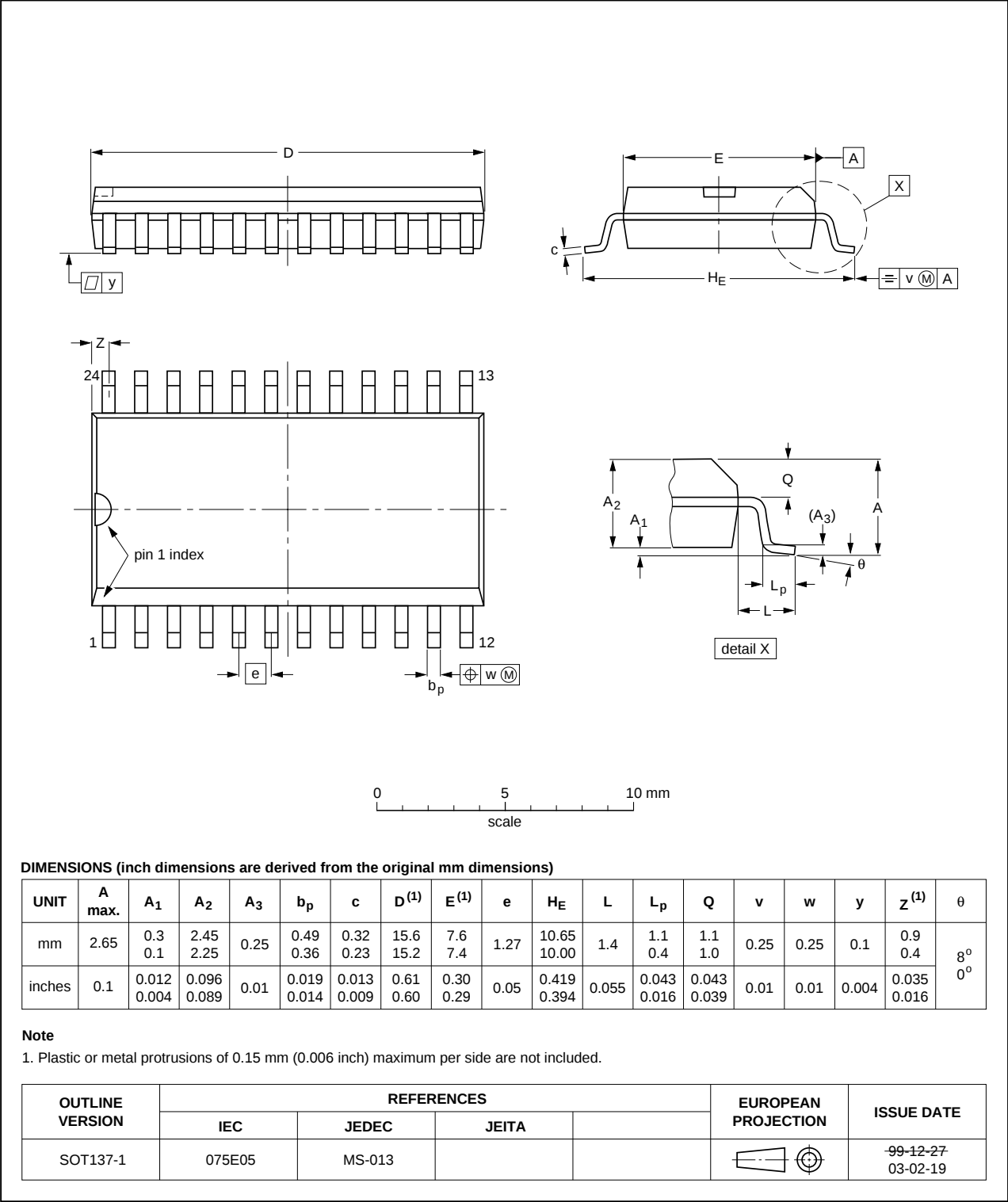


Fig 9. Package outline SOT137-1 (SO24)

SSOP24: plastic shrink small outline package; 24 leads; body width 5.3 mm

SOT340-1

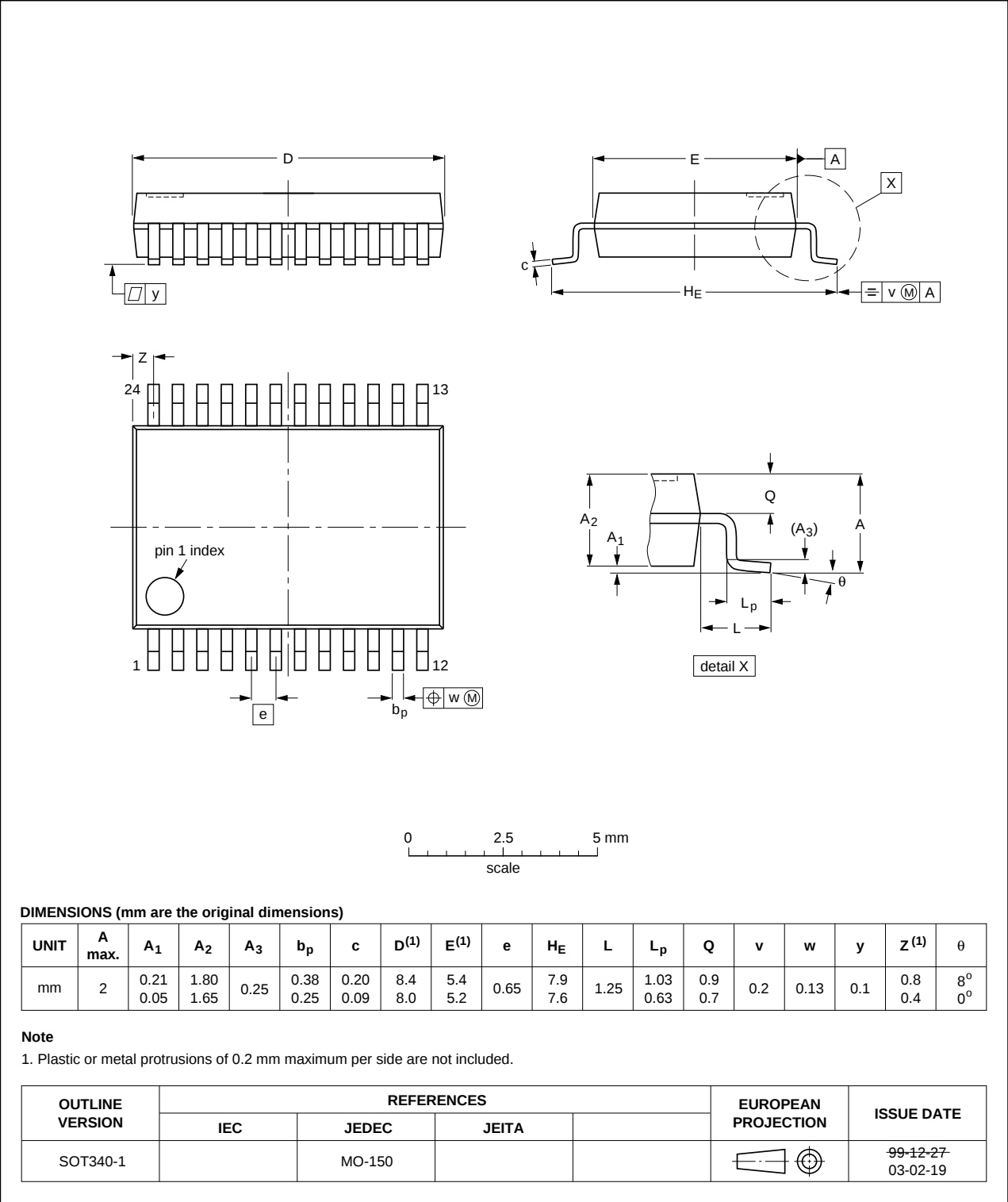


Fig 10. Package outline SOT340-1 (SSOP24)

TSSOP24: plastic thin shrink small outline package; 24 leads; body width 4.4 mm

SOT355-1

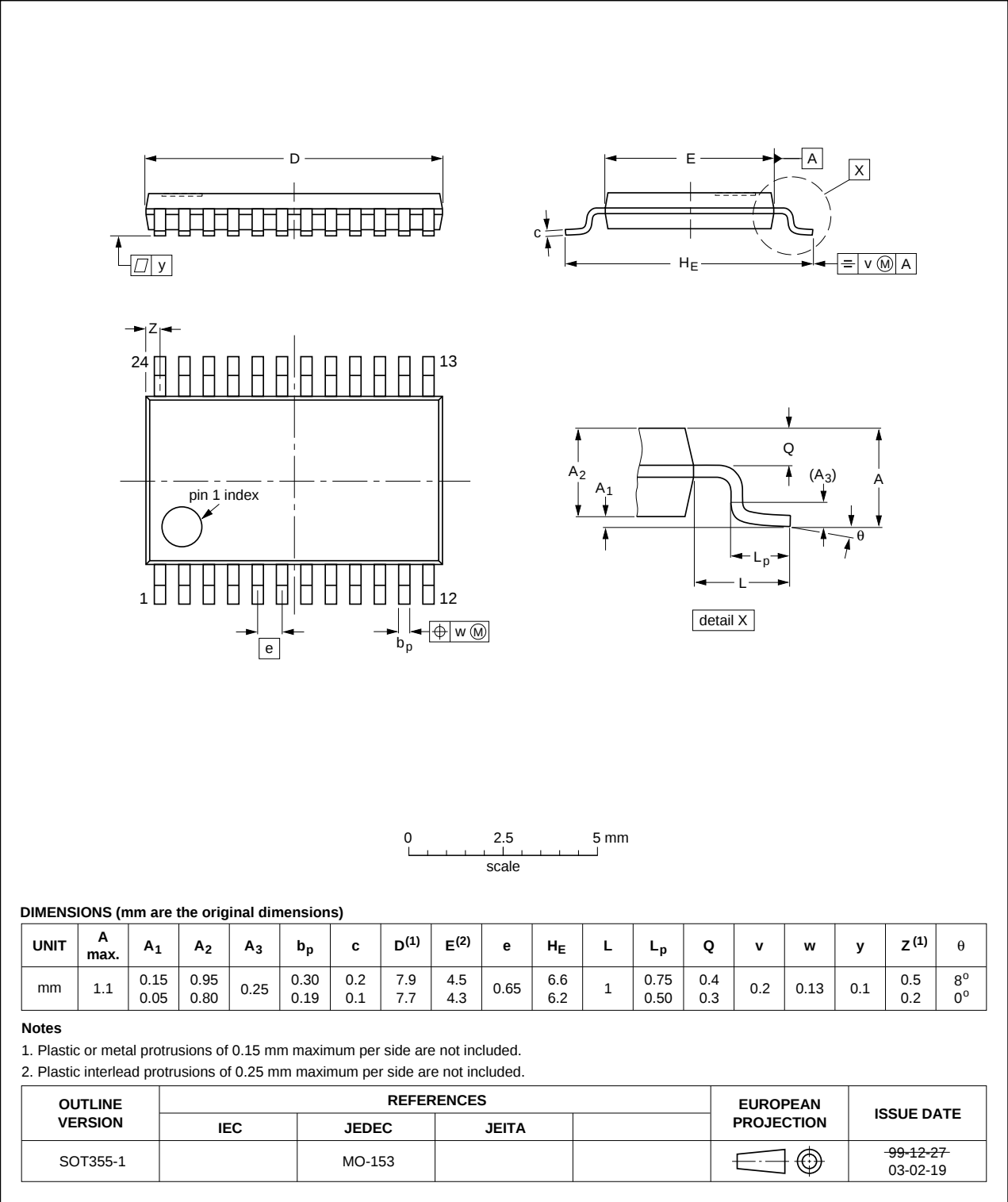


Fig 11. Package outline SOT355-1 (TSSOP24)

DHVQFN24: plastic dual in-line compatible thermal enhanced very thin quad flat package;
no leads; 24 terminals; body 3.5 x 5.5 x 0.85 mm

SOT815-1

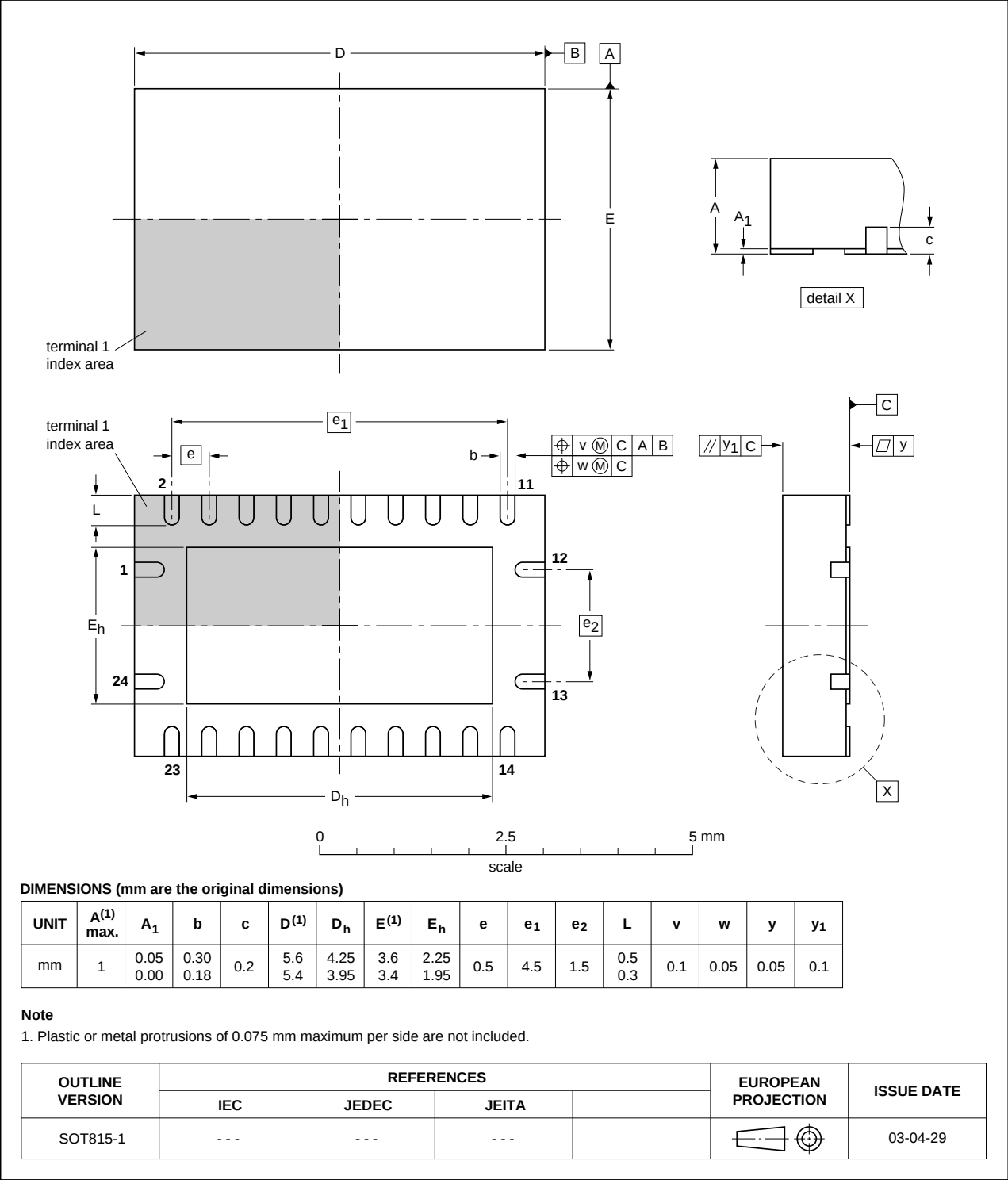


Fig 12. Package outline SOT815-1 (DHVQFN24)

13. Abbreviations

Table 9. Abbreviations

Acronym	Description
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

14. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVC4245A v.10	20121218	Product data sheet	-	74LVC4245A v.9
Modifications:	$V_{CC(A)}$ and $V_{CC(B)}$ changed into $V_{CC(A)}$ and $V_{CC(B)}$ (errata)			
74LVC4245A v.9	20121120	Product data sheet	-	74LVC4245A v.8
Modifications:	Figure 4: Pin configuration drawing corrected for DHVQFN24 package			
74LVC4245A v.8	20111122	Product data sheet	-	74LVC4245A v.7
74LVC4245A v.7	20110812	Product data sheet	-	74LVC4245A v.6
74LVC4245A v.6	20080118	Product data sheet	-	74LVC4245A v.5
74LVC4245A v.5	20040330	Product specification	-	74LVC4245A v.4
74LVC4245A v.4	20040211	Product specification	-	74LVC4245A v.3
74LVC4245A v.3	19990615	Product specification	-	74LVC4245A v.2
74LVC4245A v.2	19980729	Product specification	-	74LVC4245A v.1
74LVC4245A v.1	19980729	Product specification	-	-

15. Legal information

15.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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